

DESCRIPTION

The HY51V(S)18160HG/HGL is the new generation dynamic RAM organized 1,048,576 words x 16bit. HY51V(S)18160HG/HGL has realized higher density, higher performance and various functions by utilizing advanced CMOS process technology. The HY51V(S)18160HG/HGL offers Fast Page Mode as a high speed access mode. Multiplexed address inputs permit the HY51V(S)18160HG/HGL to be packaged in standard 400mil 42pin SOJ and 44(50) pin TSOP-II. The package size provides high system bit densities and is compatible with widely available automated testing and insertion equipment. System oriented features include single power supply 3.3V +/- 0.3V tolerance, direct interfacing capability with high performance logic families such as Schottky TTL.

FEATURES

- Fast Page Mode capability
- Read-modify-write capability
- Multi-bit parallel test capability
- TTL(3.3V) compatible inputs and outputs
- /RAS only, CAS-before-/RAS, Hidden and self refresh(L-version) capability
- **Fast access time and cycle time**
- JEDEC standard pinout
- 42pin plastic SOJ/44(50)pin TSOP-II(400mil)
- Single power supply of 3.3V +/- 0.3V
- Battery back up operation (L-version)
- Self refresh operation (L-version)
- 2 /CAS byte control

Part No	tRAC	tCAC	tRC	tPC
HY51V(S)18160HG/HGL-5	50ns	13ns	90ns	35ns
HY51V(S)18160HG/HGL-6	60ns	15ns	110ns	40ns
HY51V(S)18160HG/HGL-7	70ns	18ns	130ns	45ns

• Power dissipation

	50ns	60ns	70ns
Active	684mW	612mW	540mW
Standby	7.2mW(CMOS level Max) 0.54mW (L-version : Max)		

• Refresh cycle

Part No	Ref	Normal	L-part
HY51V18160HG	1K	16ms	
HY51V18160HGL	1K		128ms

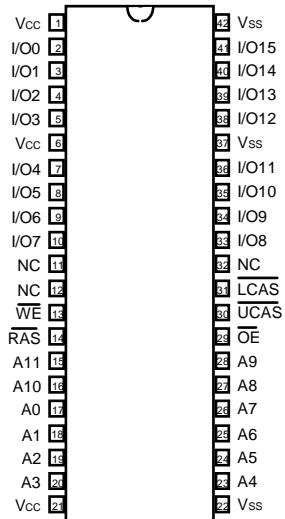
ORDERING INFORMATION

Part Number	Access Time	Package
HY51V(S)18160HGJ/HG(L)J-5 HY51V(S)18160HGJ/HG(L)J-6 HY51V(S)18160HGJ/HG(L)J-7	50ns 60ns 70ns	400mil 42pin SOJ
HY51V(S)18160HGT/HG(L)T-5 HY51V(S)18160HGT/HG(L)T-6 HY51V(S)18160HGT/HG(L)T-7	50ns 60ns 70ns	400mil 44(50)pin TSOP-II

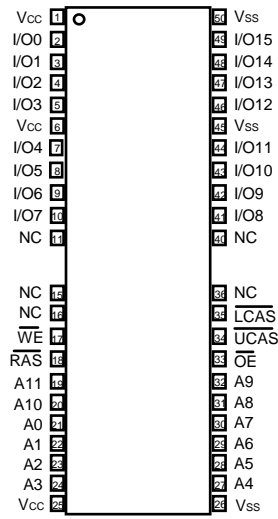
(S) : Self refresh, (L) : Low power

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PIN CONFIGURATION



42 Pin Plastic SOJ



44(50) Pin Plastic TSOP-II

PIN DESCRIPTION

Pin	Function
/RAS	Row Address Strobe
/UCAS, /LCAS	Column Address Strobe
/WE	Write Enable
/OE	Output Enable
A0-A9	Address Inputs
A0-A9	Refresh Address Inputs
I/O 0-I/O15	Data Input / Output
Vcc	Power (3.3V)
Vss	Ground
NC	No connection

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit
Ambient Temperature	TA	0 ~ 70	°C
Storage Temperature	TSTG	-55 ~ 125	°C
Voltage on Any Pin relative to Vss	VT	-0.5 ~ Vcc + 0.5 (Max 4.6V)	V
Voltage on Vcc relative to Vss	Vcc	-0.5 ~ 4.6	V
Short Circuit Output Current	IOUT	50	mA
Power Dissipation	PT	1	W

Recommended DC OPERATING CONDITIONS (TA=0 to 70 °C)

Parameter	Symbol	Min	Typ.	Max	Unit	Note
Power Supply Voltage	Vcc	3.0	3.3	3.6	V	
Input High Voltage	VIH	2.0	-	Vcc + 0.3	V	
Input Low Voltage	VIL	-0.3	-	0.8	V	

Note : All voltages are referenced to Vss

Truth Table

/RAS	/LCAS	/UCAS	/WE	/OE	Output	Operation		Notes
H	D	D	D	D	Open	Standby		1,3
L	L	H	H	L	Valid	Lower byte	Read cycle	1, 3
L	H	L	H	L	Valid	Upper byte		
L	L	L	H	L	Valid	Word		
L	L	H	L	D	Open	Lower byte	Early write cycle	1, 2, 3
L	H	L	L	D	Open	Upper byte		
L	L	L	L	D	Open	Word		
L	L	H	L	H	Undefined	Lower byte	Delayed write cycle	1, 2, 3
L	H	L	L	H	Undefined	Upper byte		
L	L	L	L	H	Undefined	Word		
L	L	H	H to L	L to H	Valid	Lower byte	Read-modify-write Cycle	1, 3
L	H	L	H to L	L to H	Valid	Upper byte		
L	L	L	H to L	L to H	Valid	Word		
H to L	H	L	D	D	Open	Word	CBR refresh or Self refresh (L-series)	1, 3
H to L	L	H	D	D	Open	Word		
H to L	L	L	D	D	Open	Word		
L	H	H	D	D	Open	Word	/RAS only refresh cycle	1, 3
L	L	L	H	H	Open	Read cycle (Output disabled)		1, 3

Notes :

1. H : High (inactive) L : Low (active) D : H or L
2. $twcs \geq 0ns$ Early write cycle
 $twcs \leq 0ns$ Delayed write cycle
3. Mode is determined by the OR function of the /UCAS and /LCAS (mode is set by earliest of /UCAS and /LCAS active edge and reset by the latest of /UCAS and /LCAS inactive edge), However write operation and output High-Z control are done independently by each /UCAS, /LCAS
 ex) if /RAS = H to L, /UCAS = H, /LCAS = L, then /CAS-before-/RAS refresh cycle is selected

DC CHARACTERISTICS ($V_{CC} = 3.3V \pm 10\%$, $T_A = 0$ to $70^\circ C$)

Symbol	Parameter	Min	Max	Unit	Note	
VOH	Output Level Output Level voltage(I _{out} = -2mA)	2.4	V _{CC}	V		
VOL	Output Level Output Level voltage(I _{out} =2mA)	0	0.4	V		
ICC1	Operating current Average power supply operating current (/RAS, /CAS Cycling : t _{RC} = t _{RC} min)	50ns	-	190	mA	1, 2
		60ns	-	170		
		70ns	-	150		
ICC2	Standby current (TTL interface) Power supply standby current (/RAS, /CAS=V _{IH} , D _{out} = High-Z)	-	2	mA		
ICC3	/RAS only refresh current Average power supply current /RAS only refresh mode (t _{RC} = t _{RC} min)	50ns	-	190	mA	2
		60ns	-	170		
		70ns	-	150		
ICC4	Fast page mode current Average power supply current Fast page mode (t _{PC} =t _{PC} min)	50ns	-	185	mA	1, 3
		60ns	-	165		
		70ns	-	145		
ICC5	CMOS interface (/RAS, /CAS $\geq V_{CC}-0.2V$, D _{out} = High-Z)	-	1	mA		
	Standby current (L-version)	-	150	uA	4	
ICC6	/CAS-before-/RAS refresh current (t _{RC} =t _{RC} min)	50ns	-	190	mA	
		60ns	-	170		
		70ns	-	150		
ICC7	Battery back up operating current (standby with CBR refresh) (t _{RC} =31.3us, t _{RAS} \leq 0.3us, D _{out} =High-Z)	-	400	uA	4	
ICC8	Standby current (/RAS = V _{IH} , /CAS = V _{IL} , D _{out} =Enable)	-	5	uA	1	
ICC9	Self refresh current (/RAS, /CAS \leq 0.2V, D _{out} =High-Z, CMOS interface)	-	250	uA	4	
II(L)	Input leakage current, Any input (0V \leq V _{in} \leq 4.6V)	-10	10	uA		
IO(L)	Output leakage current, (D _{out} is disabled, 0V \leq V _{out} \leq 4.6V)	-10	10	uA		

Note :

1. Icc depends on output load condition when the device is selected, Icc(max) is specified at the output open condition
2. Address can be changed once or less while /RAS=V_{IL}
3. Address can be changed once or less while /UCAS and /LCAS =V_{IH}
4. /UCAS = L (\leq 0.2) and /LCAS=L (\leq 0.2) while /RAS=L (\leq 0.2)
5. L-Version

CAPACITANCE ($V_{CC}=3.3V \pm 10\%$, $T_A=25^\circ C$)

Parameter	Symbol	Min.	Max	Unit	Note
Input capacitance (Address)	CI1	-	5	pF	1
Input capacitance (Clocks)	CI2	-	7	pF	1
Output capacitance (Data-in, Data-out)	CI/O	-	7	pF	1, 2

Note : 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.
 2. /UCAS and /LCAS = V_{IH} to disable D_{out}

AC CHARACTERISTICS ($V_{CC}=3.3V \pm 10\%$, $T_A=0-70^\circ C$, Note 1, 2, 18, 19, 20)

Test Condition

- Input rise and fall times = 5ns
- Input timing reference level : $V_{IL}/V_{IH} = 0.8/2.0V$
- Output timing reference level : $V_{OL}/V_{OH}=0.8/0.2V$
- Output load : 1 TTL gate + CL (100pF) (including scope and jig)

Read, Write, Read-modify-Write and Refresh Cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
Random read or write cycle time	tRC	90	-	110	-	130	-	ns	
/RAS precharge time	tRP	30	-	40	-	50	-	ns	
/CAS precharge time	tCP	8	-	10	-	10	-	ns	24
/RAS pulse width	tRAS	50	10,000	60	10,000	70	10,000	ns	
/CAS pulse width	tCAS	13	10,000	15	10,000	18	10,000	ns	
Row address set-up time	tASR	0	-	0	-	0	-	ns	
Row address hold time	tRAH	8	-	10	-	10	-	ns	
Column address set-up time	tASC	0	-	0	-	0	-	ns	21
Column address hold time	tCAH	8	-	10	-	15	-	ns	21
/RAS to /CAS delay time	tRCD	18	45	20	45	20	52	ns	3
/RAS to Column address delay time	tRAD	13	30	15	30	15	35	ns	4
/RAS hold time	tRSH	13	-	15	-	18	-	ns	
/CAS hold time	tCSH	50	-	60	-	70	-	ns	23
/CAS to /RAS precharge time	tCRP	5	-	5	-	5	-	ns	22

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Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
/OE to Din delay time	tODD	13	-	15	-	18	-	ns	5
/OE delay time from Din	tDZO	0	-	0	-	0	-	ns	6
/CAS delay time from Din	tDZC	0	-	0	-	0	-	ns	6
Transition time (Rise and Fall)	tT	3	50	3	50	3	50	ns	7
Refresh period	tREF	-	16	-	16	-	16	ms	1K Ref.
Refresh period (L-version)		-	128	-	128	-	128	ms	1K Ref.

Read Cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
Access time from /RAS	tRAC	-	50	-	60	-	70	ns	8,9
Access time from /CAS	tCAC	-	13	-	15	-	18	ns	9,10,17
Access time from column address	tAA	-	25	-	30	-	35	ns	9,11,17
Access time from /OE	tOAC	-	13	-	15	-	18	ns	9,25
Read command set-up time	tRCS	0	-	0	-	0	-	ns	
Read command hold time to /CAS	tRCH	0	-	0	-	0	-	ns	12,22
Read command hold time to /RAS	tRRH	5	-	5	-	5	-	ns	12
Column address to /RAS lead time	tRAL	25	-	30	-	35	-	ns	
Column address to /CAS lead time	tCAL	25	-	30	-	35	-	ns	
/CAS to output in low-Z	tCLZ	0	-	0	-	0	-	ns	
Output data hold time	tOH	3	-	3	-	3	-	ns	
Output data hold time from /OE	tOHO	3	-	3	-	3	-	ns	
Output buffer turn off time to /OE	tOEZ	-	13	-	15	-	15	ns	13
Output buffer turn off time	tOFF	-	13	-	15	-	15	ns	13
/CAS to Din delay time	tCDD	13	-	15	-	18	-	ns	5

Write Cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
Write command set-up time	tWCS	0	-	0	-	0	-	ns	14,21
Write command hold time	tWCH	8	-	10	-	15	-	ns	21
Write command pulse width	tWP	8	-	10	-	15	-	ns	
Write command to /RAS lead time	tRWL	13	-	15	-	18	-	ns	
Write command to /CAS lead time	tCWL	13	-	15	-	18	-	ns	23
Data-in set-up time	tDS	0	-	0	-	0	-	ns	15,23
Data-in hold time	tDH	8	-	10	-	15	-	ns	15,23

Read-Modify-Write Cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
Read-modify-write cycle time	tRWC	131	-	155	-	181	-	ns	
/RAS to /WE delay time	tRWD	73	-	85	-	98	-	ns	14
/CAS to /WE delay time	tCWD	36	-	40	-	46	-	ns	14
Column address to /WE delay time	tAWD	48	-	55	-	63	-	ns	14
/OE hold time from /WE	tOEH	13	-	15	-	18	-	ns	

Refresh cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
/CAS set-up time (/CAS-before-/RAS Refresh Cycle)	tCSR	5	-	5	-	5	-	ns	21
/CAS hold time (/CAS-before-/RAS Refresh Cycle)	tCHR	8	-	10	-	10	-	ns	22
/RAS precharge to /CAS hold time (/CAS-before-/RAS Refresh Cycle)	tRPC	5	-	5	-	5	-	ns	21

Fast Page Mode Cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
Fast page mode cycle time	tPC	35	-	40	-	45	-	ns	
Fast page mode /RAS pulse width	tRASP	-	100K	-	100K	-	100K	ns	16
Access time from /CAS precharge	tACP	-	30	-	35	-	40	ns	9,17,22
/RAS hold time from /CAS precharge	tRHCP	30	-	35	-	40	-	ns	

Fast Page Mode Read-Modify-Write Cycle

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
Fast Page read-modify-write cycle time	tPRWC	76	-	85	-	96	-	ns	
Fast page mode read-modify-write cycle /CAS precharge to /WE delay time	tCPW	53	-	60	-	68	-	ns	14,22

Self Refresh Cycle (L-Version)

Parameter	Symbol	-50		-60		-70		Unit	Note
		Min	Max	Min	Max	Min	Max		
/RAS pulse width (self refresh)	tRASS	100	-	100	-	100	-	us	
/RAS precharge time (self refresh)	tRPS	90	-	110	-	130	-	ns	
/CAS hold time (self refresh)	tCHS	-50	-	-50	-	-50	-	ns	

Notes :

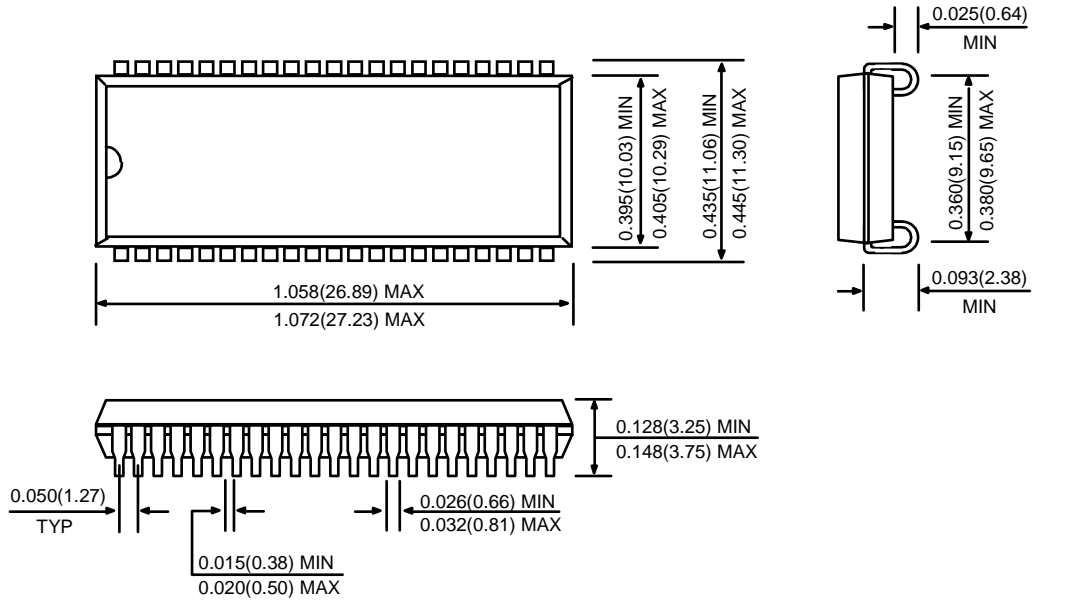
1. AC measurements assume $t_r = 5\text{ns}$
2. AC initial pause of 200 μs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing /RAS-only refresh or /CAS-before-/RAS refresh)
3. Operation with the $t_{\text{RCDD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met, $t_{\text{RCDD}}(\text{max})$ is specified as a reference point only : if t_{RCDD} is greater than the specified $t_{\text{RCDD}}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
4. Operation with the $t_{\text{RAD}}(\text{max})$ limit insures that $t_{\text{RAC}}(\text{max})$ can be met, $t_{\text{RAD}}(\text{max})$ is specified as a reference point only : if t_{RAD} is greater than the specified $t_{\text{RAD}}(\text{max})$ limit, then access time is controlled exclusively by t_{AA} .
5. Either t_{ODD} or t_{CDD} must be satisfied.
6. Either t_{DZO} or t_{DZC} must be satisfied.
7. $V_{\text{IH}}(\text{min})$ and $V_{\text{IL}}(\text{max})$ are reference levels for measuring timing of input signals, also transition times are measured between $V_{\text{IH}}(\text{min})$ and $V_{\text{IL}}(\text{max})$
8. Assumes that $t_{\text{RCDD}} \leq t_{\text{RCDD}}(\text{max})$ and $t_{\text{RAD}} \leq t_{\text{RAD}}(\text{max})$. If t_{RCDD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown
9. Measured with a load circuit equivalent to 1 TTL loads and 100pF.($V_{\text{OH}}=2.0\text{V}$, $V_{\text{OL}}=0.8\text{V}$)
10. Assumes that $t_{\text{RCDD}} \geq t_{\text{RCDD}}(\text{max})$ and $t_{\text{RCDD}} + t_{\text{CAC}}(\text{max}) \geq t_{\text{RAD}} + t_{\text{AA}}(\text{max})$
11. Assumes that $t_{\text{RAD}} \geq t_{\text{RAD}}(\text{max})$ and $t_{\text{RCDD}} + t_{\text{CAC}}(\text{max}) \leq t_{\text{RAD}} + t_{\text{AA}}(\text{max})$
12. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles
13. $t_{\text{OFF}}(\text{max})$, $t_{\text{OEZ}}(\text{max})$, $t_{\text{OFR}}(\text{max})$ and $t_{\text{WEZ}}(\text{max})$ define the time at which the outputs achieve the open circuit condition and is not referenced to output voltage levels
14. t_{WCS} , t_{RWD} , t_{CWD} , t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only : If $t_{\text{WCS}} \geq t_{\text{WCS}}(\text{min})$, the cycle is an early write cycle and the data out pin will remain open circuit(high impedance) throughout the entire cycle : If $t_{\text{RWD}} \geq t_{\text{RWD}}(\text{min})$, $t_{\text{CWD}} \geq t_{\text{CWD}}(\text{min})$, $t_{\text{AWD}} \geq t_{\text{AWD}}(\text{min})$, the cycle is a read-modify-write and the data output will contain data read from the selected cell : if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
15. These parameters are referenced to /UCAS and /LCAS leading edge in early write cycles and to /WE leading edge in delayed write or read-modify-write cycles
16. t_{RASP} defines /RAS pulse width in Fast page mode cycles

17. Access time is determined by the longest among t_{AA} or t_{CAC} or t_{ACP}
18. In delayed write or read-modify-write cycles, OE must disable output buffer prior to applying data to the device, After /RAS is reset, if $t_{OE} \geq t_{CWL}$, the I/O pin will remain open circuit (high impedance)
If $t_{OE} < t_{CWL}$, invalid data will be out at each I/O
19. When both /UCAS and /LCAS go low at the same time, all 16 bit data are written into the device
/UCAS and /LCAS cannot be staggered within the same write / read cycles.
20. All the Vcc and Vss pins shall be supplied with the same voltages
21. t_{ASC} , t_{CAH} , t_{RCS} , t_{WCS} , t_{WCH} , t_{CSR} and t_{RPC} are determined by the earlier falling edge of /UCAS or /LCAS.
22. t_{CRP} , t_{CHR} , t_{RCH} , t_{ACP} and t_{CPW} are determined by the later rising edge of /UCAS or /LCAS.
23. t_{CWL} , t_{DH} , t_{DS} and t_{CSH} should be satisfied by both /UCAS and /LCAS
24. t_{CP} is determined by that time the both /UCAS and /LCAS are high.
25. When output buffers are enabled once, sustain the low impedance state until valid data is obtained
When output buffer is turned on and off within a very short time, generally it causes large Vcc/Vss line noise, which causes to degrade $V_{IH \text{ min}}$ / $V_{IL \text{ max}}$ level
26. Please do not use t_{RASS} timing, $10\mu s \leq t_{RASS} \leq 100\mu s$. During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{RASS} \geq 100\mu s$, then /RAS precharge time should use t_{RPS} instead of t_{RP}
27. H or L (H : $V_{IH(\text{min})} \leq V_{IN} \leq V_{IH(\text{max})}$, L : $V_{IL(\text{min})} \leq V_{IN} \leq V_{IL(\text{max})}$)

PACKAGE INFORMATION

42pin SOJ

Unit: Inches (mm)



44(50)pin TSOP II

